

## Silicon wafer wire cutting fluid DK-760D

### 【Performance and use】

Silicon wafer wire cutting fluid DK-760D is used for diamond wire cutting of semiconductor materials like monocrystalline silicon, polycrystalline silicon, wafers, and ceramics. It is formulated with surfactants, lubricants, EP additives, and other auxiliaries, making it an environmentally friendly, fully synthetic wire cutting fluid.

### 【Main technical parameters】

item	Technical indicators	Technical indicators
External view	Light yellow transparent liquid	Light yellow transparent liquid
pH value	9.5 ± 0.5	9.5 ± 0.5
Defoaming (ml)	2 or less	2 or less
Specific weight (g/ml)	1.10 ± 0.10	1.10 ± 0.10
Surface tension (dyn/cm)	30 or less	30 or less
Storage stability	conjunctive	conjunctive
corrosiveness	Grade A cast iron	Grade A cast iron
Rust resistance	Grade A cast iron	Grade A cast iron

### 【Product advantage】

1. not corrupt, long service life.
2. Good rust resistance, no irritation to the skin.
3. Excellent powder sedimentation, the use of powder will not block the steel wire.
4. Excellent lubricity, cooling, cleaning, strong adhesion, good processing performance.

**【Instruction】**

- The working liquid is diluted with 10-20 times tap water or deionized water.
- In the course of use, the clean working liquid can be replenished at a concentration of 3-5%.
- Avoid mixing with other oils.

**【Packaging】**

18L/ barrel, 25L/ barrel, 200L/ barrel.

**【Note】**

1. This product should not be mixed with other emulsions, semi-synthetic liquids, and fully synthetic liquids, because even if the system contains a small amount of rotten residual liquid, it will affect the use effect of the new liquid.
2. the production batch is not the same, the cutting fluid may have color differences, does not affect the normal use.